

## CLAIMS

What is claimed is:

1. A heat-dissipating fin module comprising:
  - a heat-conductive base, which is installed on a heat-generating component of an electronic device;
  - a plurality of first heat-dissipating fins, which are vertically installed at intervals on one half side of the heat-conductive base, each of the first heat-dissipating fins having an arc surface parallel to one another, and the space between adjacent first heat-dissipating fins forming a first airflow space for providing a curved airflow path; and
  - a plurality of second heat-dissipating fins, which are vertically installed at intervals on the other half side of the heat-conductive base, each of the second heat-dissipating fins having an arc surface parallel to one another but having curvature centers opposite to those of the first heat-dissipating fins, and the space between adjacent second heat-dissipating fins forming a second airflow space for providing a curved airflow path that does not cross the airflow path of the first airflow space.
2. The heat-dissipating fin module of claim 1, wherein the first heat-dissipating fins and the second heat-dissipating fins are equal in length.
3. The heat-dissipating fin module of claim 1, wherein the curvature centers of the first heat-dissipating fins and the second heat-dissipating fins are on the same line.
4. The heat-dissipating fin module of claim 1, wherein the outermost first heat-dissipating fin and second heat-dissipating fin are shorter.
5. The heat-dissipating fin module of claim 1, wherein the first heat-dissipating fins

and the second heat-dissipating fins are installed on the heat-conductive base by a method selected from gluing and welding.

6. The heat-dissipating fin module of claim 1, wherein the first heat-dissipating fins and the second heat-dissipating fins are formed on the heat-conductive base by cutting and  
5 squeezing.

7. The heat-dissipating fin module of claim 1, wherein the first heat-dissipating fins and the second heat-dissipating fins have trimmed sides.

8. The heat-dissipating fin module of claim 1 further comprising at least one third heat-dissipating fin installed vertically in the outer region between the first heat-dissipating  
10 fins and the second heat-dissipating fins on the heat-conductive base.

9. The heat-dissipating fin module of claim 8, wherein the third heat-dissipating fin is straight.

10. The heat-dissipating fin module of claim 8, wherein the third heat-dissipating fin is installed by a method selected from gluing and welding.

15 11. The heat-dissipating fin module of claim 8, wherein the third heat-dissipating fin is formed by cutting and squeezing.

12. A heat-dissipating fin module comprising:

a heat-conductive base, which is installed on a heat-generating component of an electronic device;

20 a plurality of first heat-dissipating fins, which are vertically installed at intervals on one half side of the heat-conductive base, each of the first heat-dissipating fins having an arc surface parallel to one another, and the space between adjacent first heat-dissipating fins forming a first airflow space for providing a curved airflow path;

a plurality of second heat-dissipating fins, which are vertically installed at intervals on the other half side of the heat-conductive base, each of the second heat-dissipating fins having an arc surface parallel to one another but having curvature centers opposite to those of the first heat-dissipating fins, and the space between adjacent second heat-dissipating fins forming a second airflow space for providing a curved airflow path that does not cross the airflow path of the first airflow space; and

at least one third heat-dissipating fin, which is vertically installed on the heat-conductive base in an outer region between the first heat-dissipating fins and the second heat-dissipating fins.

13. The heat-dissipating fin module of claim 12, wherein the first heat-dissipating fins and the second heat-dissipating fins are equal in length.

14. The heat-dissipating fin module of claim 12, wherein the curvature centers of the first heat-dissipating fins and the second heat-dissipating fins are on the same line.

15. The heat-dissipating fin module of claim 12, wherein the outermost first heat-dissipating fin and second heat-dissipating fin are shorter.

16. The heat-dissipating fin module of claim 12, wherein the third heat-dissipating fin is straight.

17. The heat-dissipating fin module of claim 12, wherein the first heat-dissipating fins, the second heat-dissipating fins, and the third heat-dissipating fins are installed on the heat-conductive base by a method selected from gluing and welding.

18. The heat-dissipating fin module of claim 12, wherein the first heat-dissipating fins, the second heat-dissipating fins, and the third heat-dissipating fins are formed on the heat-conductive base by cutting and squeezing.